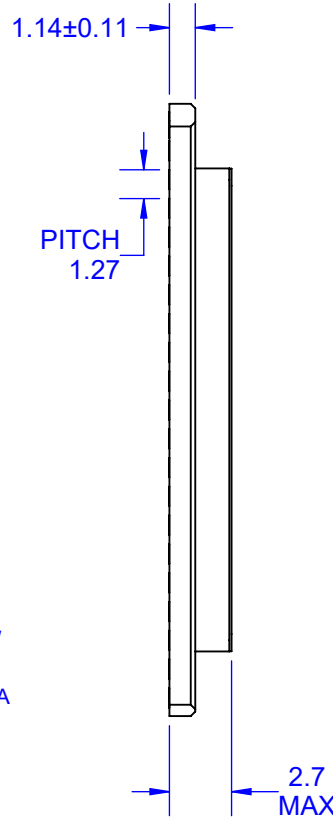
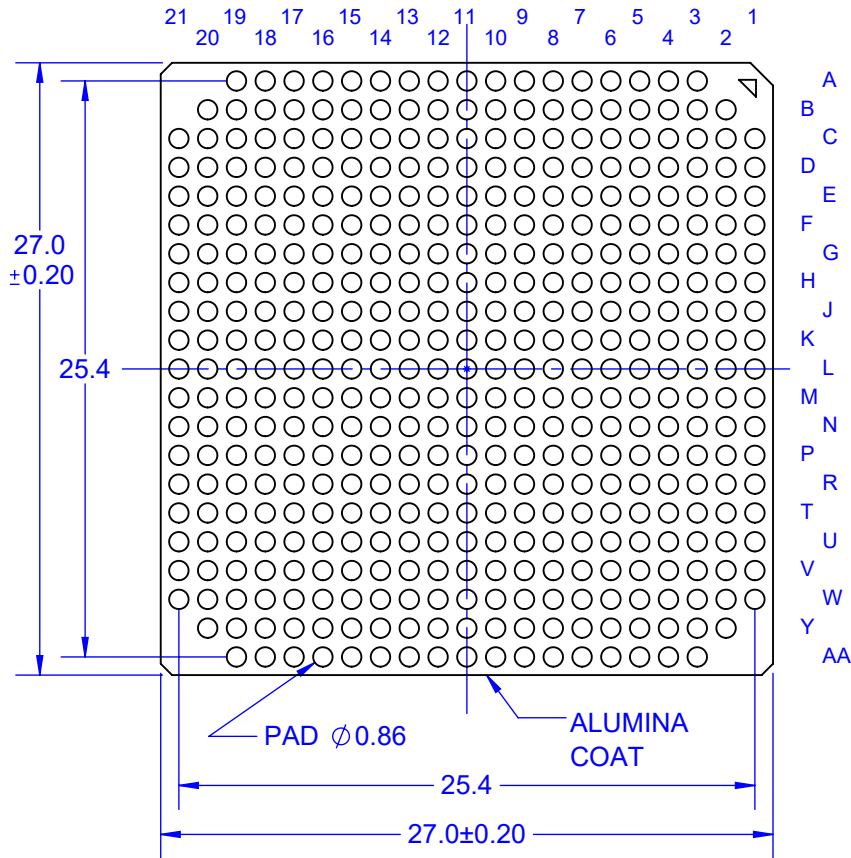
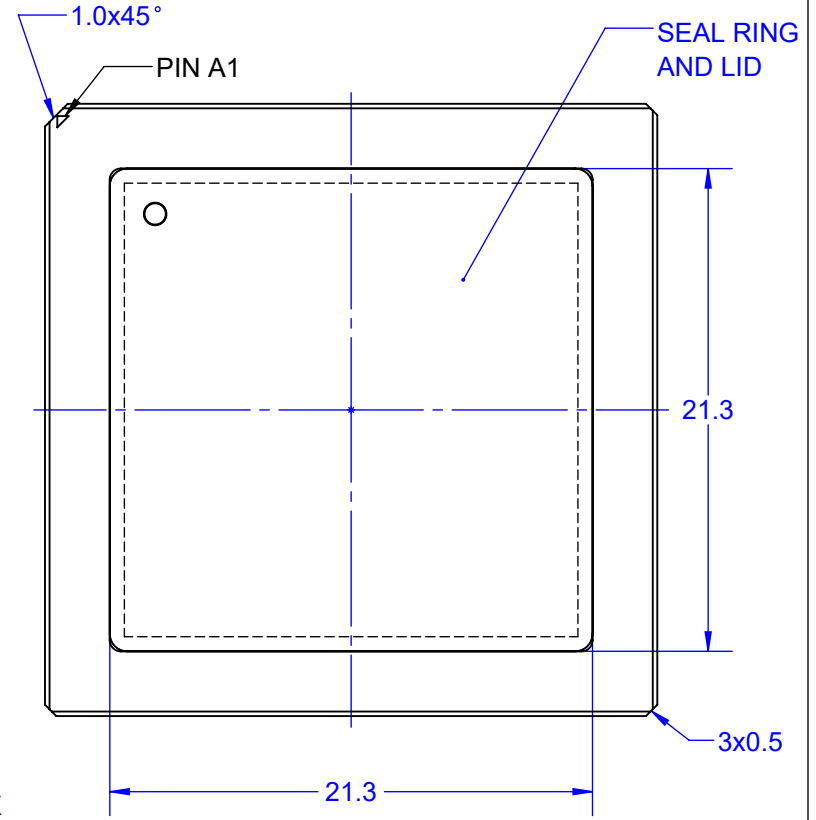


### BOTTOM VIEW



### TOP VIEW



NOTES:  
1. PLATING TOP AND BOTTOM.  
ELECTROLESS Ni 3.2~8.89  $\mu$ m (125~350 micro-inch).  
ELECTROLESS Au 0.25  $\mu$ m (10 micro-inch) MAX.

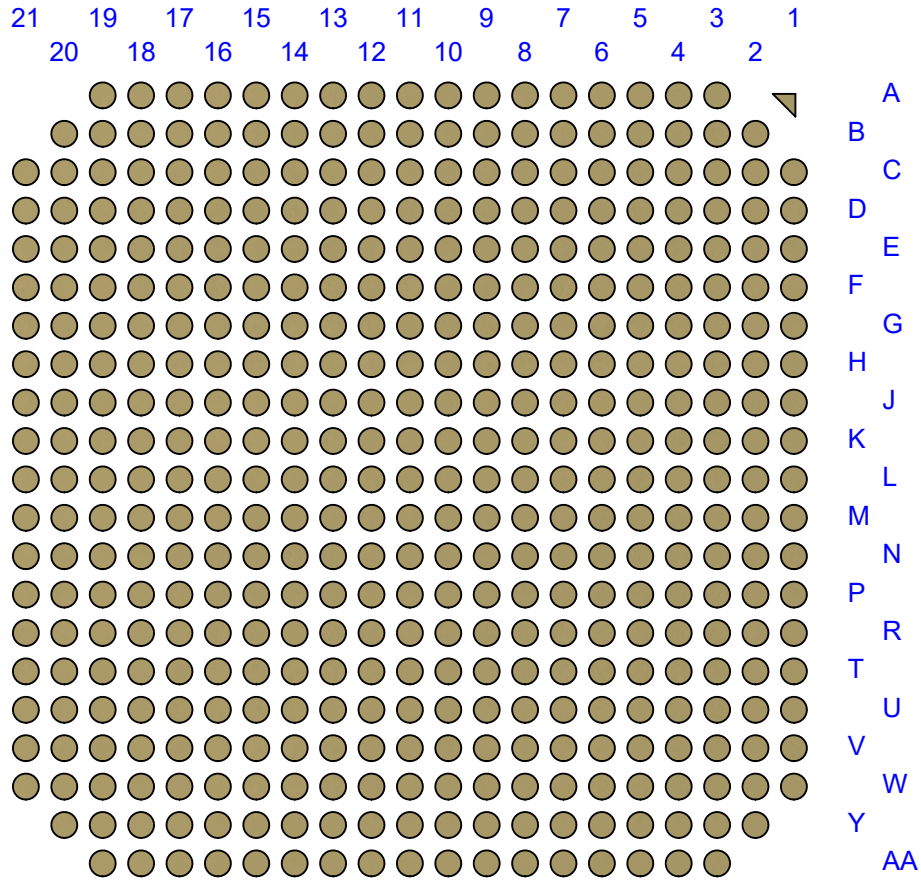
Notes: (Unless Otherwise Specified).  
1) DIMENSIONS ARE IN mm.  
2) CLGA SHOWN WITHOUT COLUMNS.  
3) SHOWN WITH HEAT SINK.

PART NUMBER OPTIONS			
PART NUMBER	DIE	SOLDER PIN	HEAT SINK
CLGA429T1.27-21x21	YES	NONE	YES

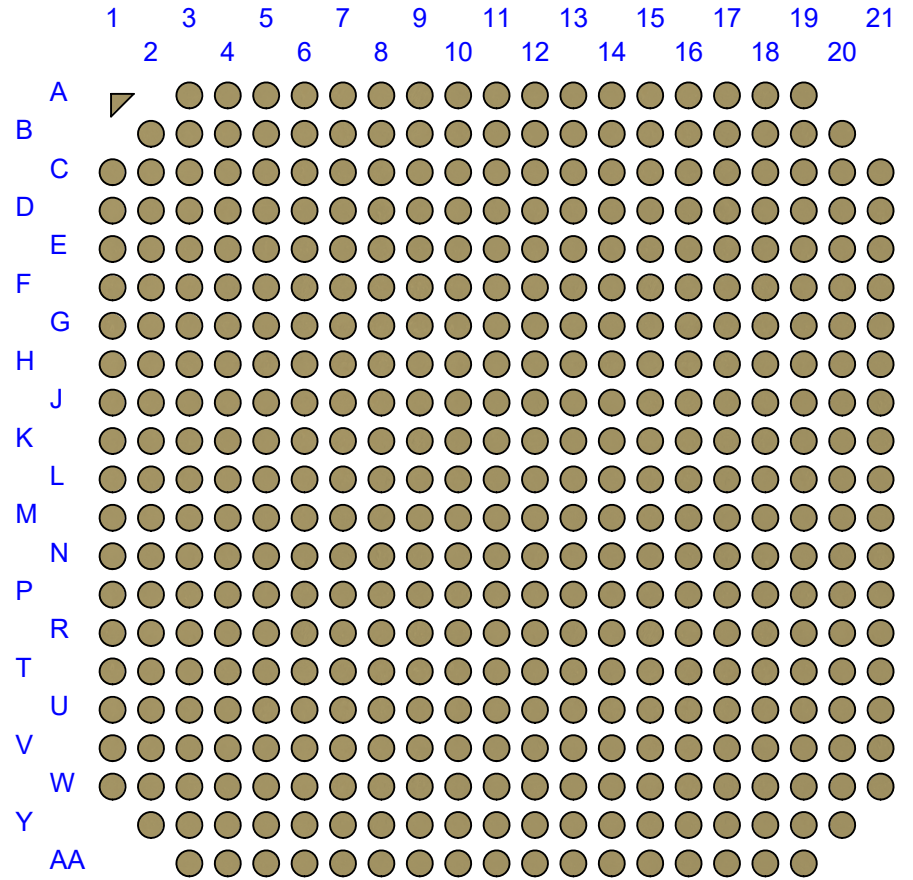
APPROVALS	DATE	<b>TopLine®</b>			
DRAWN T. Au	12/29/2021				
ENG M. Hart	12/29/2021	TITLE CLGA429T1.27-21x21 CERAMIC LAND GRID ARRAY			
MFG		SCALE 3:1	SIZE A	DRAWING NO. 160117	REV A
QA		DO NOT SCALE DRAWING			SHEET 1 OF 3
CUST					
REVISED					

# PAD PATTERN

## COLUMN (PAD) VIEW



## BOTTOM X-RAY VIEWED FROM TOP



**TopLine®**

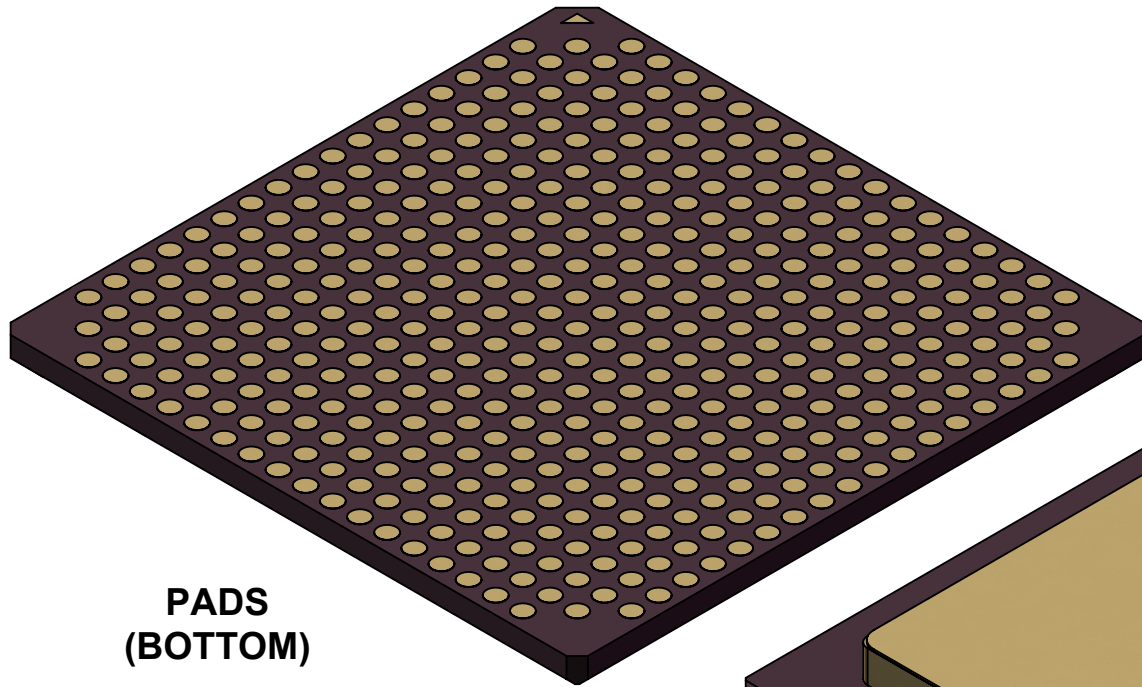
TITLE CLGA429T1.27-21x21  
CERAMIC LAND GRID ARRAY

SCALE 4:1	SIZE A	DRAWING NO. 160117	REV A
--------------	-----------	-----------------------	----------

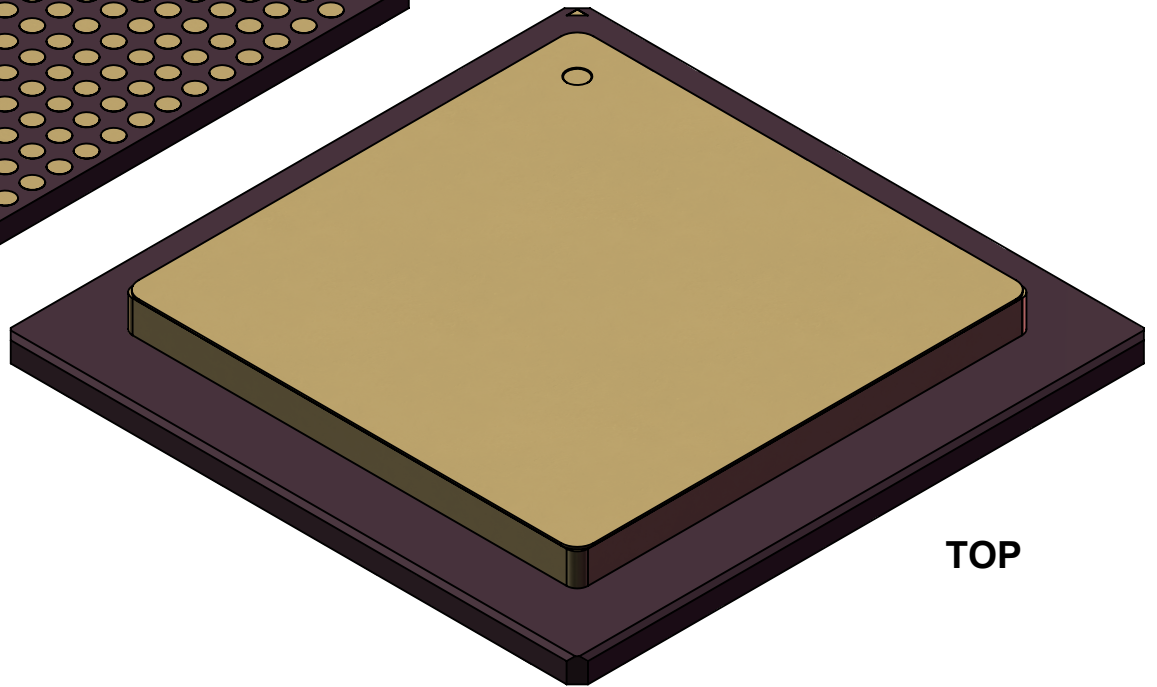
DO NOT SCALE DRAWING

SHEET 2 OF 3

**MODEL  
CLGA429T1.27-21x21  
LID ATTACHED**



**PADS  
(BOTTOM)**



**TOP**

**TopLine®**

TITLE CLGA429T1.27-21x21  
CERAMIC LAND GRID ARRAY

SCALE	SIZE	DRAWING NO.	REV
6:1	A	160117	A

DO NOT SCALE DRAWING

SHEET 3 OF 3